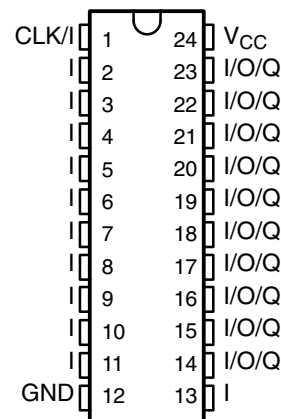
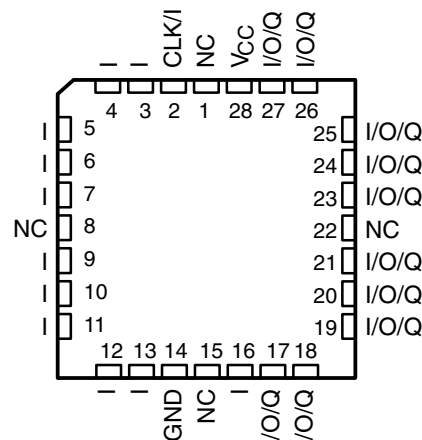


HIGH-PERFORMANCE **IMPACT-X™** PROGRAMMABLE ARRAY LOGIC CIRCUITS

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- **Second-Generation PLD Architecture**
- **High-Performance Operation:**  
 $f_{\max}$  (External Feedback) . . . 33.3 MHz  
 Propagation Delay . . . 20 ns Max
- **Increased Logic Power – Up to 22 Inputs and 10 Outputs**
- **Increased Product Terms – Average of 12 per Output**
- **Variable Product Term Distribution**  
 Allows More Complex Functions to Be Implemented
- **Each Output Is User Programmable for Registered or Combinational Operation, Polarity, and Output Enable Control**
- **Power-Up Clear on Registered Outputs**
- **TTL-Level Preload for Improved Testability**
- **Extra Terms Provide Logical Synchronous Set and Asynchronous Reset Capability**
- **Fast Programming, High Programming Yield, and Unsurpassed Reliability Ensured Using Ti-W Fuses**
- **AC and DC Testing Done at the Factory Utilizing Special Designed-In Test Features**
- **Dependable Texas Instruments Quality and Reliability**
- **Package Options Include Plastic Dual-In-Line and Chip Carrier Packages**

JT OR W PACKAGE  
(TOP VIEW)FK PACKAGE  
(TOP VIEW)

NC – No internal connection  
 Pin assignments in operating mode

**description**

The TIBPAL22V10-20M is a programmable array logic device featuring high speed and functional equivalency when compared to presently available devices. They are implemented with the familiar sum-of-products (AND-OR) logic structure featuring the new concept "Programmable Output Logic Macrocell". These IMPACT-X™ circuits combine the latest Advanced Low-Power Schottky technology with proven titanium-tungsten fuses to provide reliable, high-performance substitutes for conventional TTL logic.

These devices contain up to 22 inputs and 10 outputs. They incorporate the unique capability of defining and programming the architecture of each output on an individual basis. Outputs may be registered or nonregistered and inverting or noninverting as shown in the output logic macrocell diagram. The ten potential outputs are enabled through the use of individual product terms.

Further advantages can be seen in the introduction of variable product term distribution. This technique allocates from 8 to 16 logical product terms to each output for an average of 12 product terms per output. This variable allocation of terms allows far more complex functions to be implemented than in previously available devices.

This device is covered by U.S. Patent 4,410,987.  
 IMPACT-X is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date.  
 Products conform to specifications per the terms of Texas Instruments  
 standard warranty. Production processing does not necessarily include  
 testing of all parameters.

TEXAS  
INSTRUMENTS

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**description (continued)**

Circuit design is enhanced by the addition of a synchronous set and an asynchronous reset product term. These functions are common to all registers. When the synchronous set product term is a logic 1, the output registers are loaded with a logic 1 on the next low-to-high clock transition. When the asynchronous reset product term is a logic 1, the output registers are loaded with a logic 0. The output logic level after set or reset depends on the polarity selected during programming. Output registers can be preloaded to any desired state during testing. Preloading permits full logical verification during product testing.

With features such as programmable output logic macrocells and variable product term distribution, the TIBPAL22V10-20M offers quick design and development of custom LSI functions with complexities of 500 to 800 equivalent gates. Since each of the ten output pins may be individually configured as inputs on either a temporary or permanent basis, functions requiring up to 21 inputs and a single output or down to 12 inputs and 10 outputs are possible.

A power-up clear function is supplied that forces all registered outputs to a predetermined state after power is applied to the device. Registered outputs selected as active-low power up with their outputs high. Registered outputs selected as active-high power up with their outputs low.

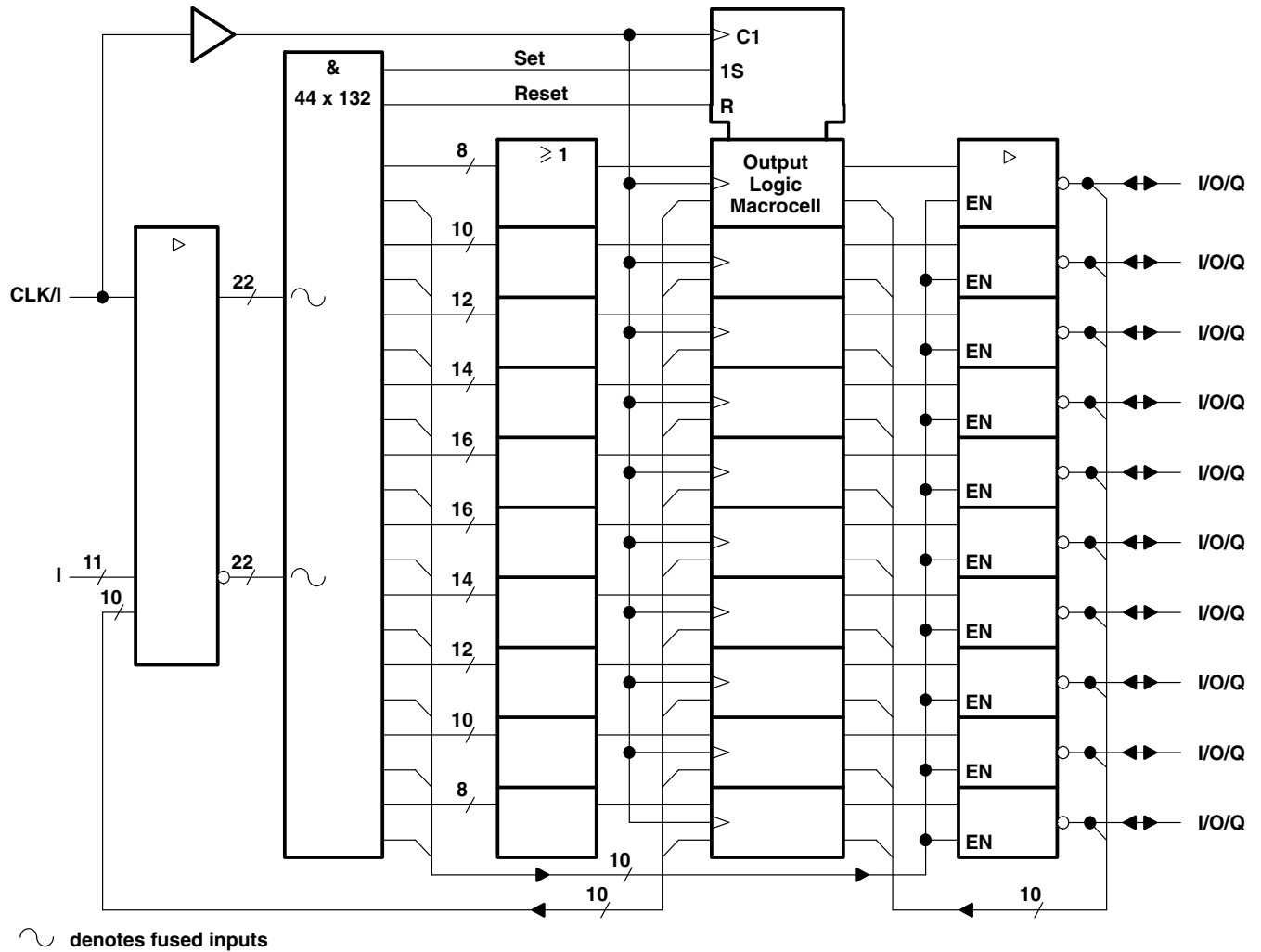
A single security fuse is provided on each device to discourage unauthorized copying of fuse patterns. Once blown, the verification circuitry is disabled and all other fuses will appear to be open.

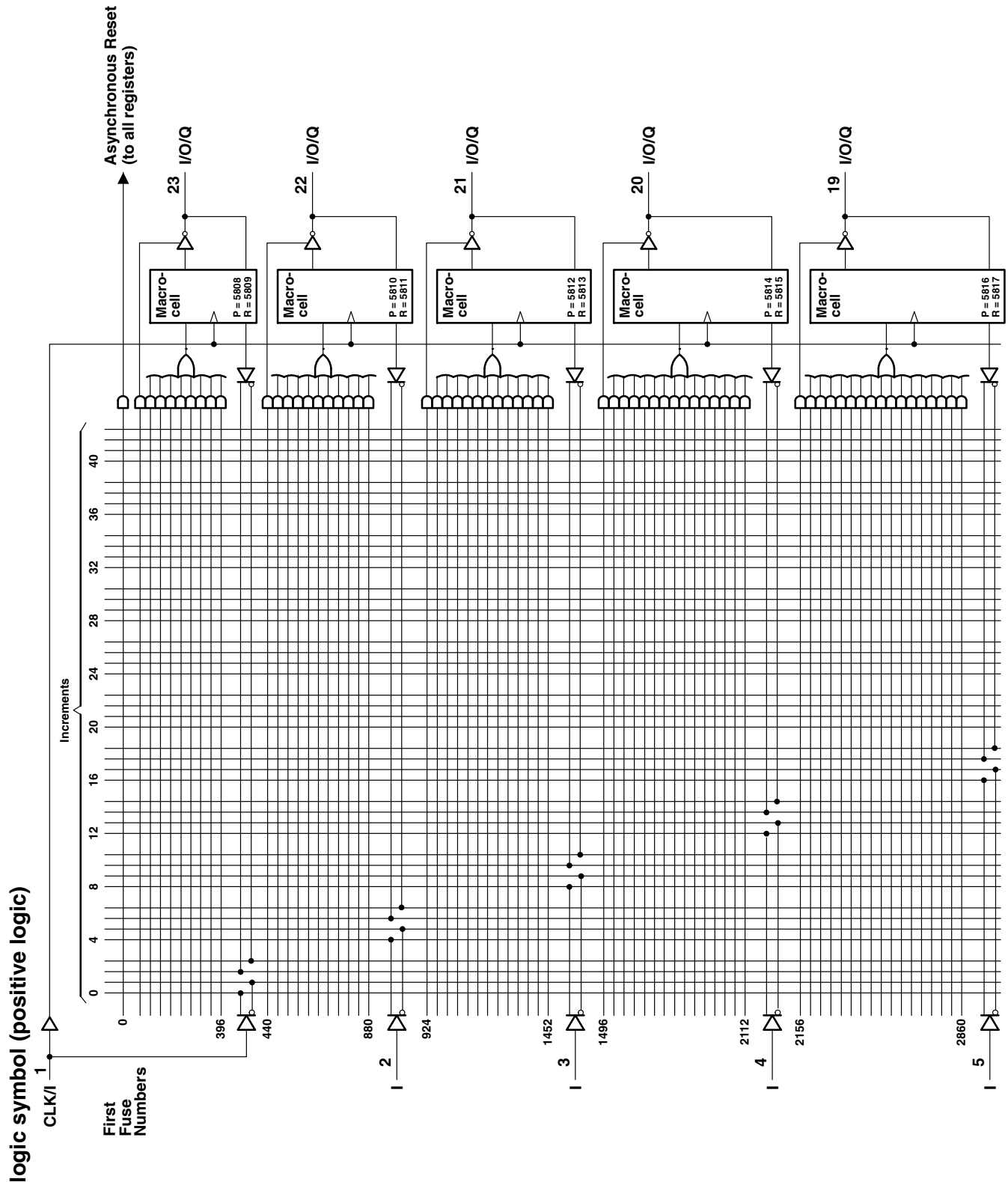
The TIBPAL22V10-20M is characterized for operation over the full military temperature range of –55°C to 125°C.

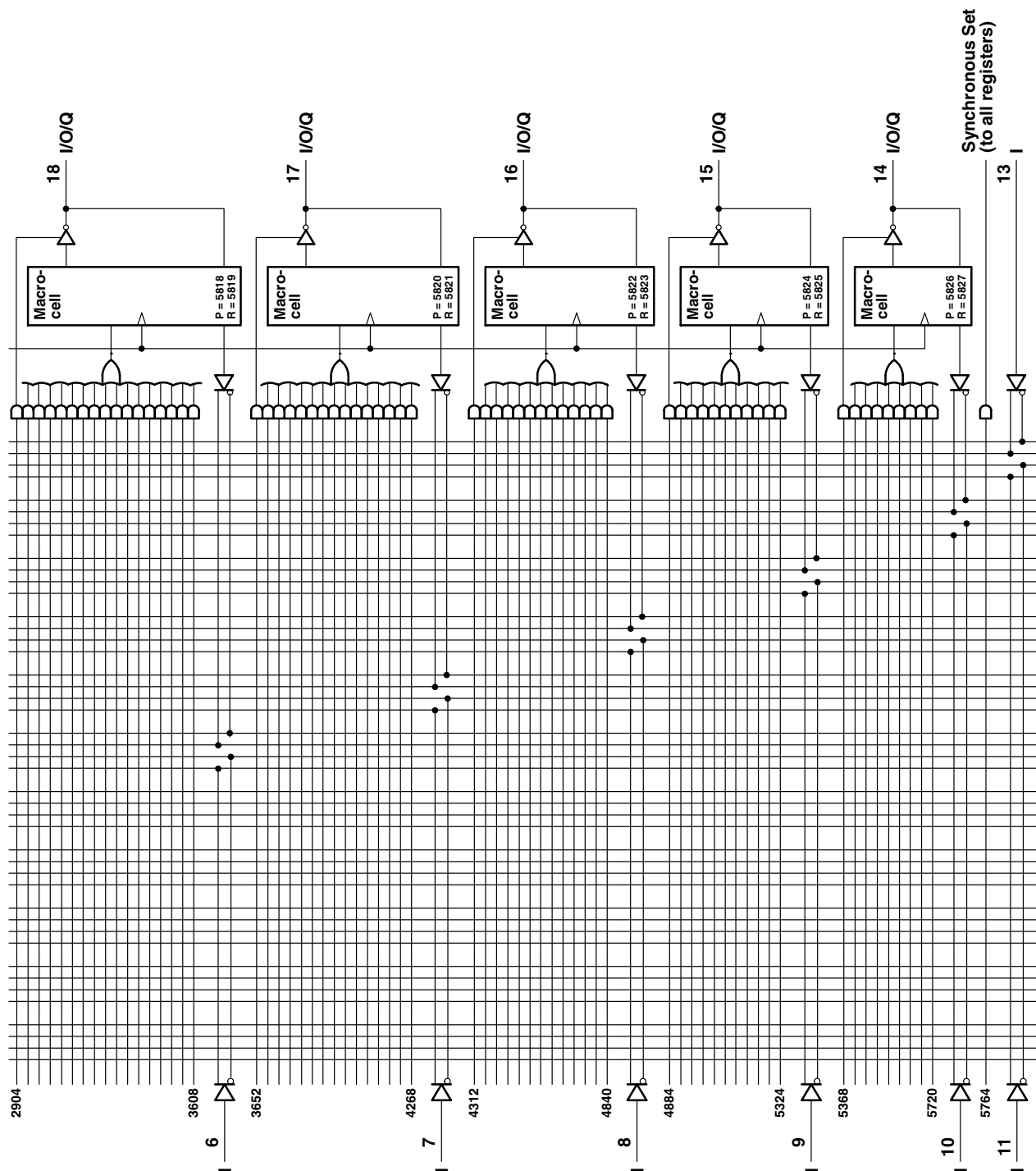
HIGH-PERFORMANCE *IMPACT-X*™ PROGRAMMABLE ARRAY LOGIC CIRCUITS

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functional block diagram (positive logic)

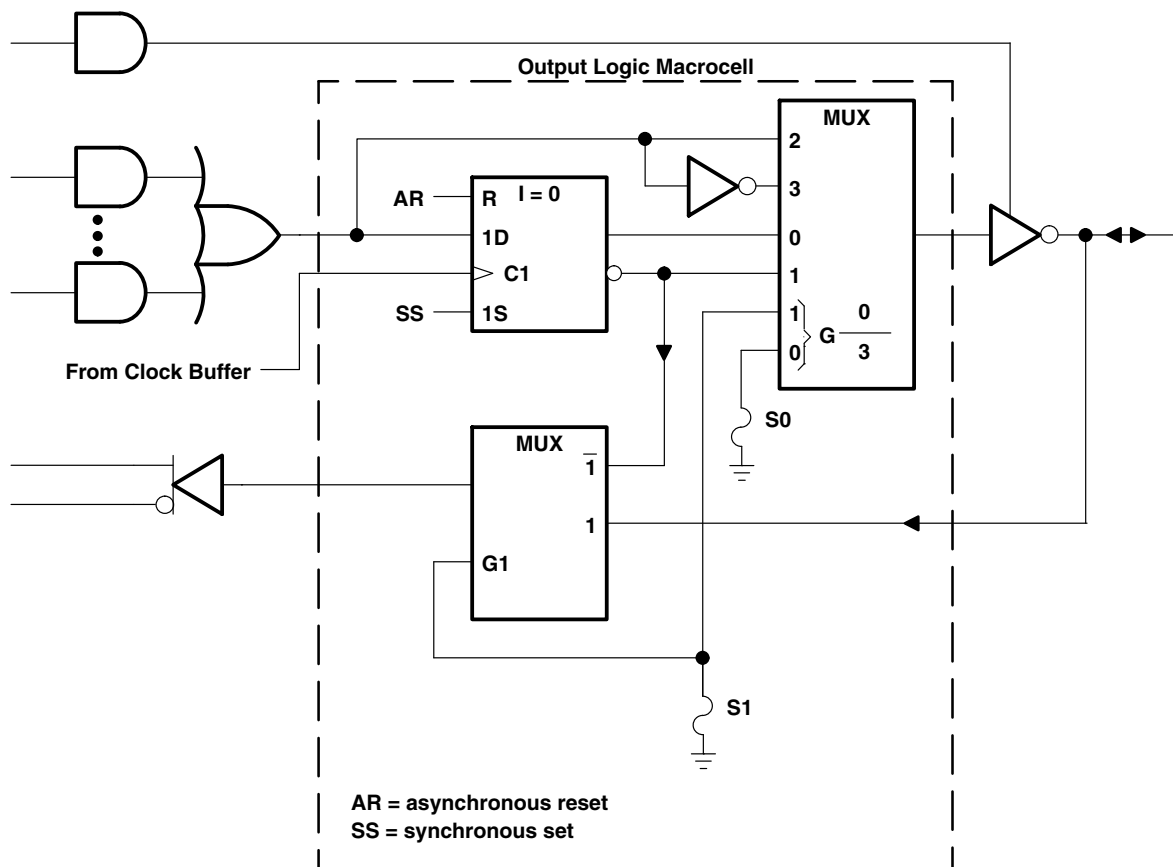


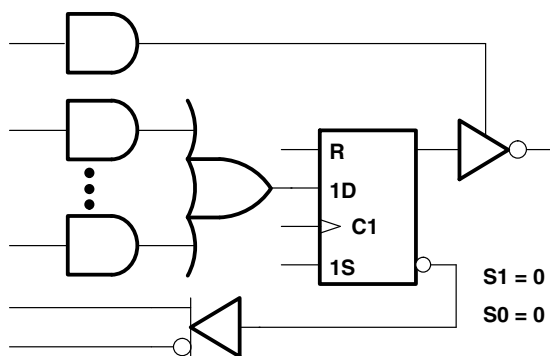




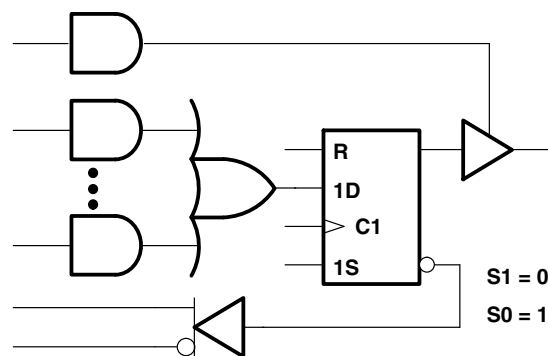
Fuse number = First fuse number + Increment  
 Inside each MACROCELL the "P" fuse is the polarity fuse and the "R" fuse is the register fuse.

### output logic macrocell diagram

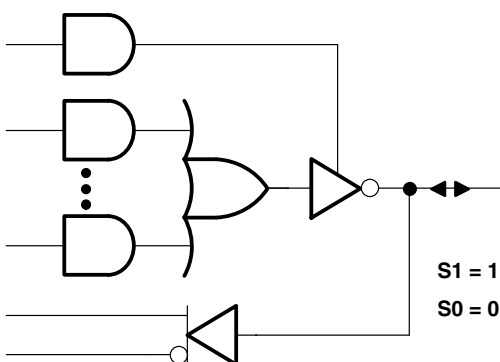




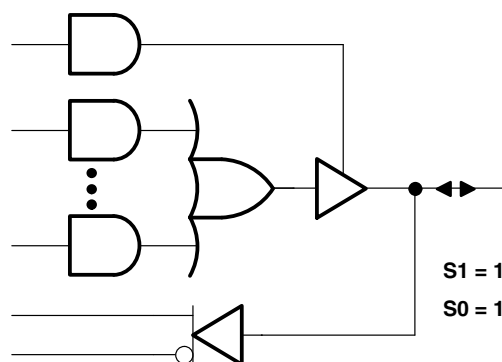
REGISTER FEEDBACK, REGISTERED, ACTIVE-LOW OUTPUT



REGISTER FEEDBACK, REGISTERED, ACTIVE-HIGH OUTPUT



I/O FEEDBACK, COMBINATIONAL, ACTIVE-LOW OUTPUT



I/O FEEDBACK, COMBINATIONAL, ACTIVE-HIGH OUTPUT

MACROCELL FEEDBACK AND OUTPUT FUNCTION TABLE

FUSE SELECT		FEEDBACK AND OUTPUT CONFIGURATION		
S1	S0			
0	0	Register feedback	Registered	Active low
0	1	Register feedback	Registered	Active high
1	0	I/O feedback	Combinational	Active low
1	1	I/O feedback	Combinational	Active high

0 = unblown fuse, 1 = blown fuse

S1 and S0 are select-function fuses as shown in the output logic macrocell diagram.

Figure 1. Resultant Macrocell Feedback and Output Logic After Programming

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**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)**

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Voltage applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	–55°C to 125°C
Storage temperature range	–65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

**recommended operating conditions**

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2		5.5	V
$V_{IL}$	Low-level input voltage			0.8	V
$I_{OH}$	High-level output current			–2	mA
$I_{OL}$	Low-level output current			12	mA
$t_w$	Pulse duration	Clock high or low		15	ns
		Asynchronous Reset high or low		20	
$t_{su}$	Setup time before clock↑	Input		17	ns
		Feedback		17	
		Synchronous Preset (active)		17	
		Asynchronous Reset (inactive)		20	
$t_h$	Hold time, input, set, or feedback after clock↑	0			ns
$T_A$	Operating free-air temperature	–55		125	°C



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## electrical characteristics over recommended operating free-air temperature range

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$			-1.2	V
$V_{OH}$	$V_{CC} = 4.5\text{ V}$ ,	$I_{OH} = -2\text{ mA}$	2.4	3.5		V
$V_{OL}$	$V_{CC} = 4.5\text{ V}$ ,	$I_{OL} = 12\text{ mA}$		0.25	0.5	V
$I_{OZH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.7\text{ V}$			0.1	mA
$I_{OZL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0.4\text{ V}$			-0.1	mA
$I_I$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 5.5\text{ V}$			1	mA
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 2.7\text{ V}$			25	μA
$I_{IL}$	CLK	$V_{CC} = 5.5\text{ V}$ , $V_I = 0.4\text{ V}$			-0.2	mA
	All others				-0.1	
$I_{OS}^\ddagger$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0.5\text{ V}$	-30		-90	mA
$I_{CC}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = \text{GND}$ , Outputs open			200	mA
$C_i$	$f = 1\text{ MHz}$ ,	$V_I = 2\text{ V}$		5.5		pF
$C_o$	$f = 1\text{ MHz}$ ,	$V_O = 2\text{ V}$		8		pF
$C_{clk}$	$f = 1\text{ MHz}$ ,	$V_{CLK} = 2\text{ V}$		7		pF

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.  $V_O$  is set at 0.5 V to avoid test problems caused by test equipment ground degradation.

## switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

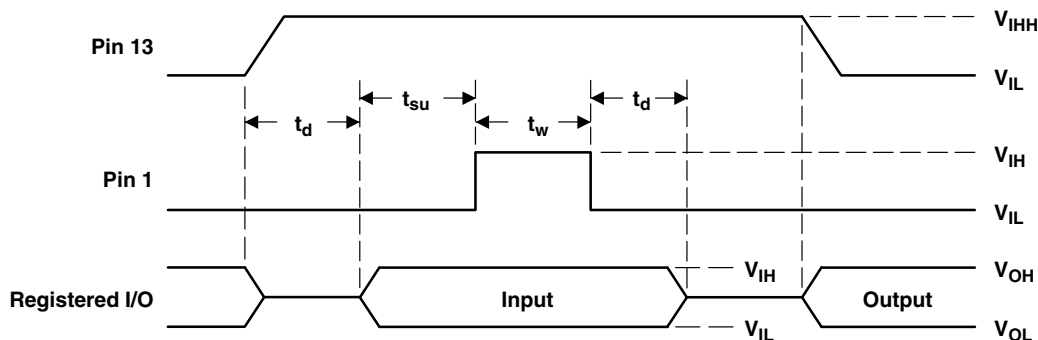
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITION	MIN	MAX	UNIT
$f_{max}^\S$	External feedback		R1 = 390 Ω, R2 = 750 Ω, See Figure 4	33.3		MHz
$t_{pd}$	I, I/O	I/O			20	ns
$t_{pd}$	I, I/O (reset)	Q			25	ns
$t_{pd}$	CLK	Q			15	ns
$t_{en}$	I, I/O	I/O, Q			20	ns
$t_{dis}$	I, I/O	I/O, Q			20	ns

$$^\S f_{max} \text{ (with feedback)} = \frac{1}{t_{su} + t_{pd}(\text{CLK to Q})}$$
 Verification of  $t_{su}$  and  $t_{pd}(\text{CLK to Q})$  may be used to verify expected performance.

**preload procedure for registered outputs (see Notes 2 and 3)**

The output registers can be preloaded to any desired state during device testing. This permits any state to be tested without having to step through the entire state-machine sequence. Each register is preloaded individually by following the steps given below:

- Step 1. With  $V_{CC}$  at 5 V and pin 1 at  $V_{IL}$ , raise pin 13 to  $V_{IHH}$ .
- Step 2. Apply either  $V_{IL}$  or  $V_{IH}$  to the output corresponding to the register to be preloaded.
- Step 3. Pulse pin 1, clocking in preload data.
- Step 4. Remove output voltage, then lower pin 13 to  $V_{IL}$ . Preload can be verified by observing the voltage level at the output pin.



**Figure 2. Preload Waveforms**

NOTES: 2. Pin numbers shown are for the JT package only. If chip-carrier socket adapter is not used, pin numbers must be changed accordingly.

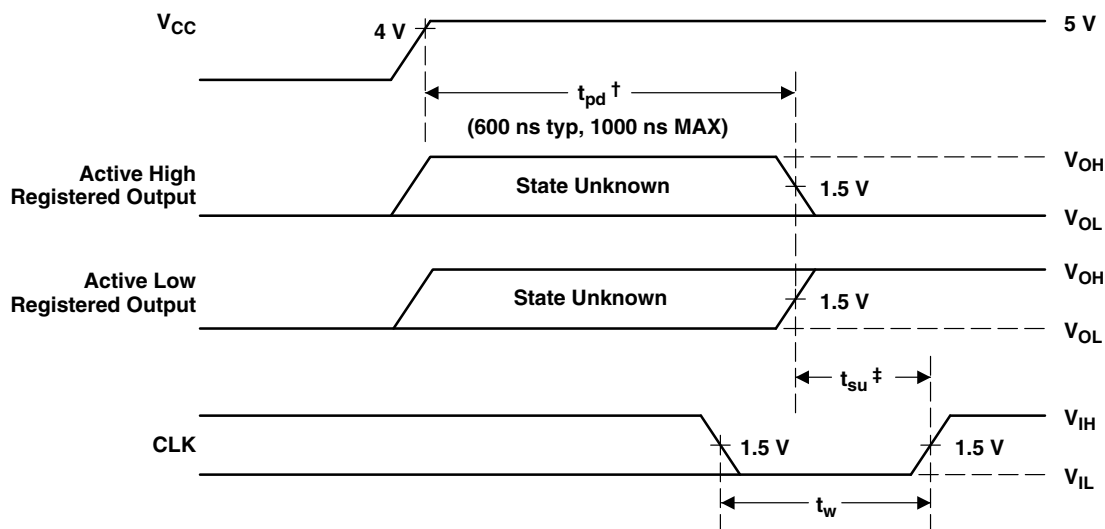
3.  $t_d = t_{su} = t_w = 100$  ns to 1000 ns.  $V_{IHH} = 10.25$  V to 10.75 V.

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**power-up reset**

Following power up, all registers are reset to zero. The output level depends on the polarity selected during programming. This feature provides extra flexibility to the system designer and is especially valuable in simplifying state-machine initialization. To ensure a valid power-up reset, it is important that the rise of  $V_{CC}$  be monotonic. Following power-up reset, a low-to-high clock transition must not occur until all applicable input and feedback setup times are met.



† This is the power-up reset time and applies to registered outputs only. The values shown are from characterization data.

‡ This is the setup time for input or feedback.

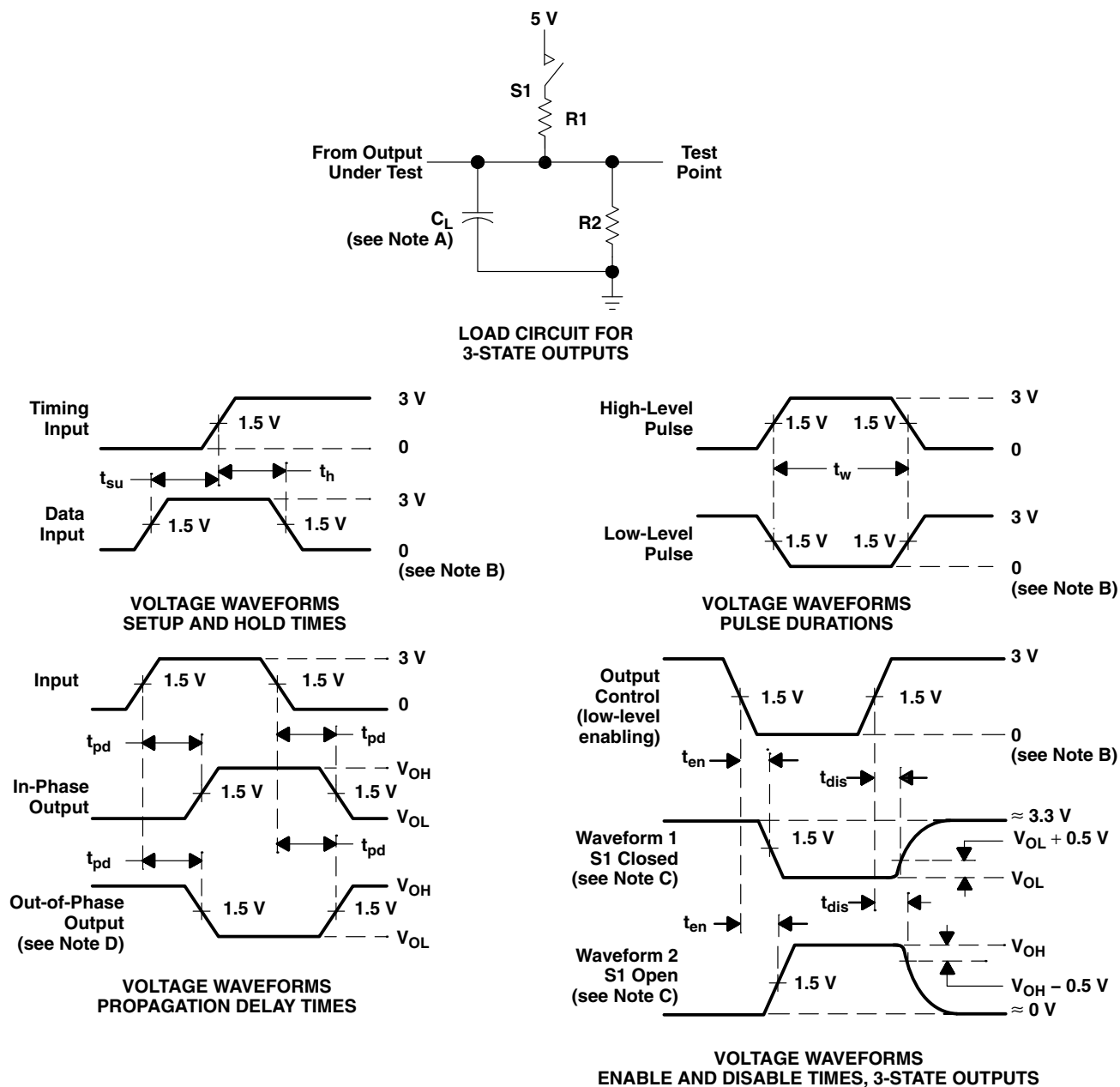
**Figure 3. Power-Up Reset Waveforms**

**programming information**

Texas Instruments programmable logic devices can be programmed using widely available software and inexpensive device programmers.

Complete programming specifications, algorithms, and the latest information on hardware, software, and firmware are available upon request. Information on programmers capable of programming Texas Instruments programmable logic is also available, upon request, from the nearest TI field sales office, local authorized TI distributor, or by calling Texas Instruments at (214) 997-5666.

## PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance and is 50 pF for  $t_{pd}$  and  $t_{en}$ , 5 pF for  $t_{dis}$ .

B. All input pulses have the following characteristics:  $PRR \leq 10$  MHz,  $t_r$  and  $t_f = 2$  ns, duty cycle = 50%.

C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

D. When measuring propagation delay times of 3-state outputs, switch S1 is closed.

E. Equivalent loads may be used for testing.

Figure 4. Load Circuit and Voltage Waveforms

## TYPICAL CHARACTERISTICS

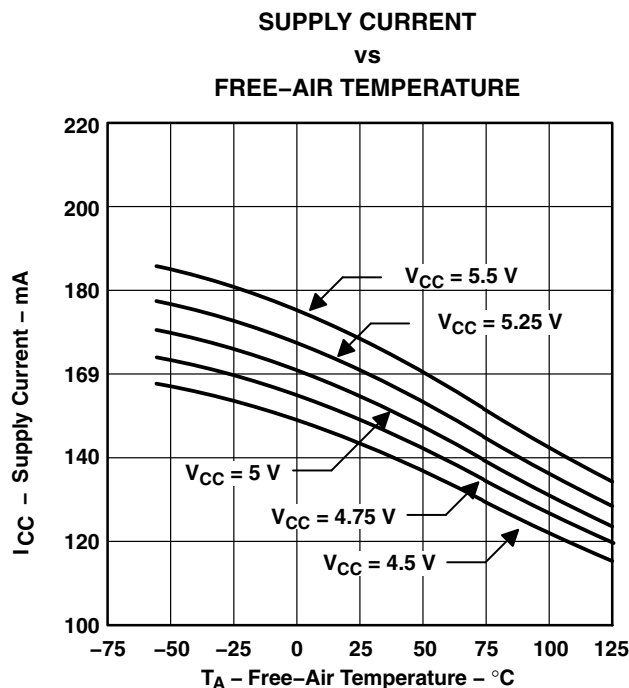


Figure 5

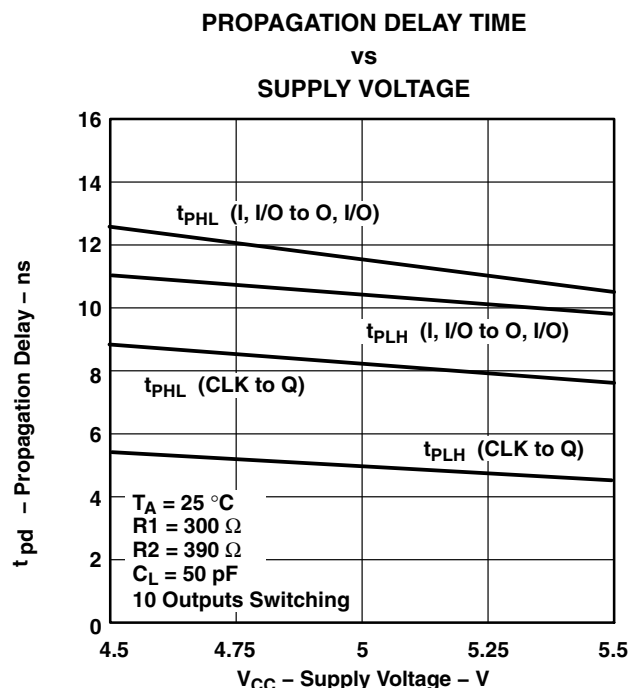


Figure 6

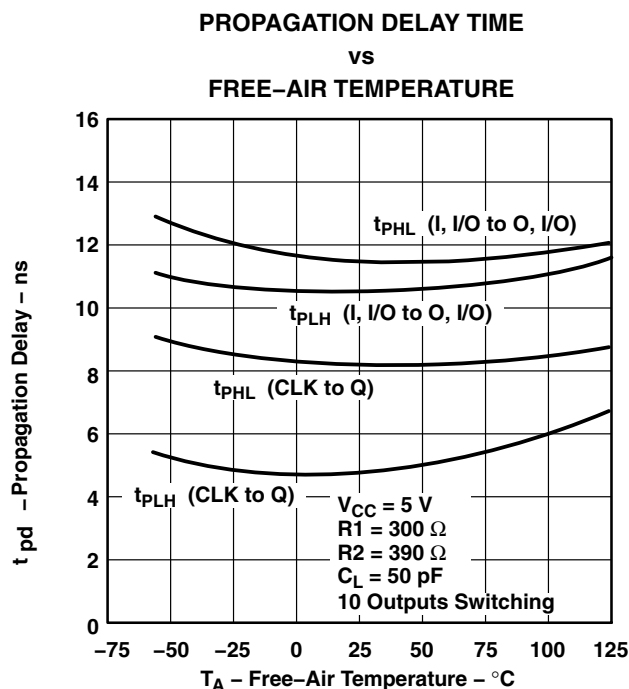


Figure 7

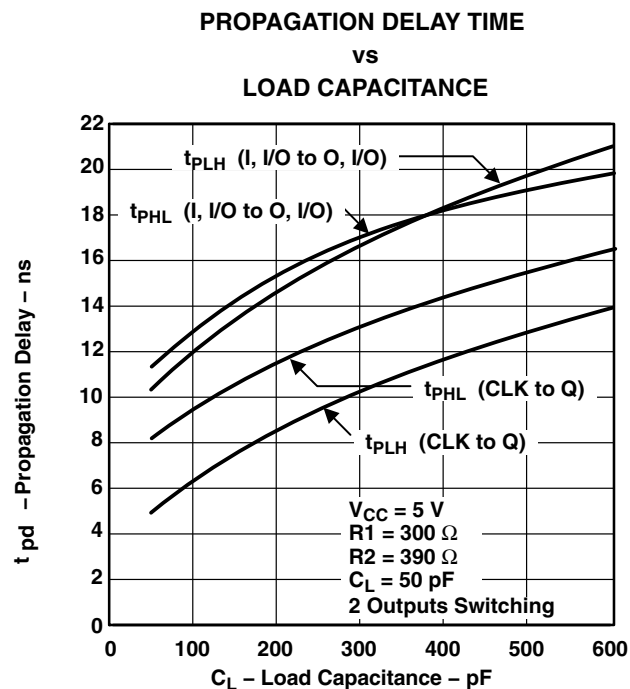


Figure 8

## TYPICAL CHARACTERISTICS

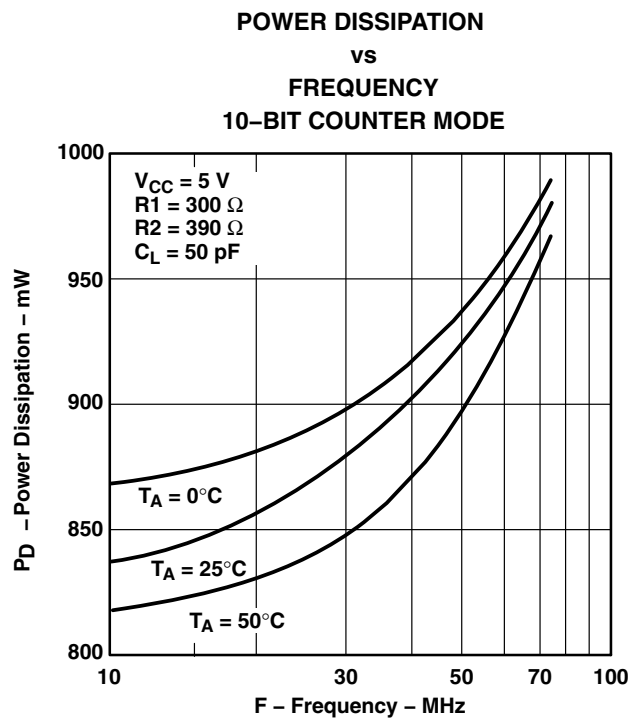


Figure 9

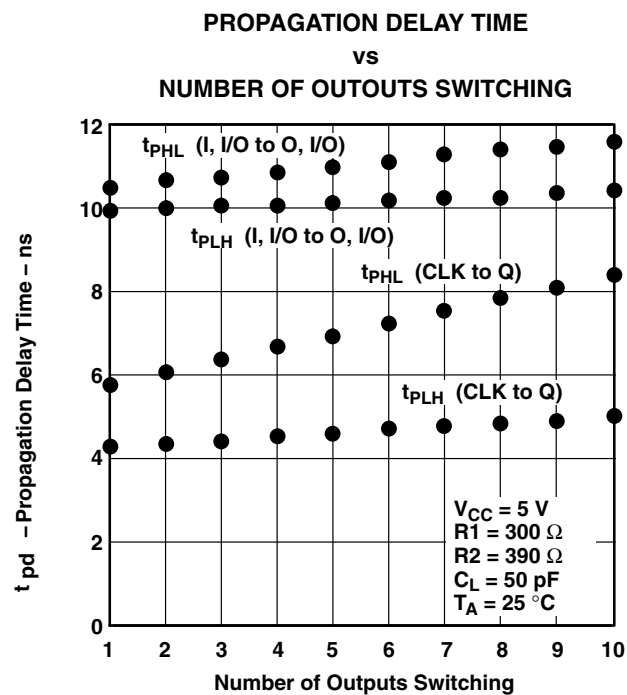


Figure 10

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
5962-86053043A	NRND	LCCC	FK	28	1	TBD	Call TI	Call TI	
5962-8605304KA	NRND	CFP	W	24	1	TBD	Call TI	Call TI	
5962-8605304LA	NRND	CDIP	JT	24	1	TBD	Call TI	Call TI	
TIBPAL22V10-20MFKB	NRND	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	
TIBPAL22V10-20MJTB	NRND	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	
TIBPAL22V10-20MWB	NRND	CFP	W	24	1	TBD	A42	N / A for Pkg Type	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

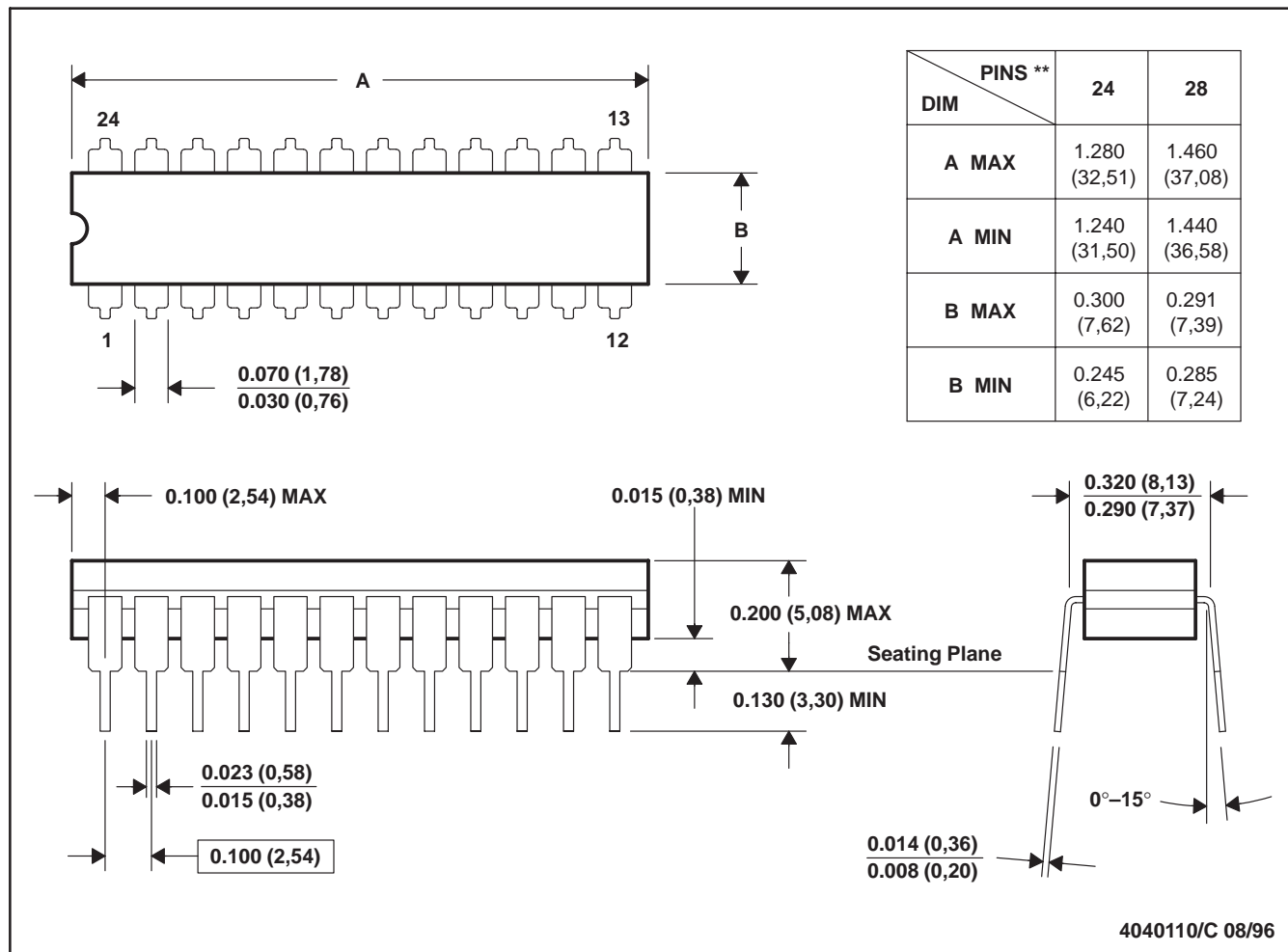
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## JT (R-GDIP-T\*\*)

## CERAMIC DUAL-IN-LINE

24 LEADS SHOWN

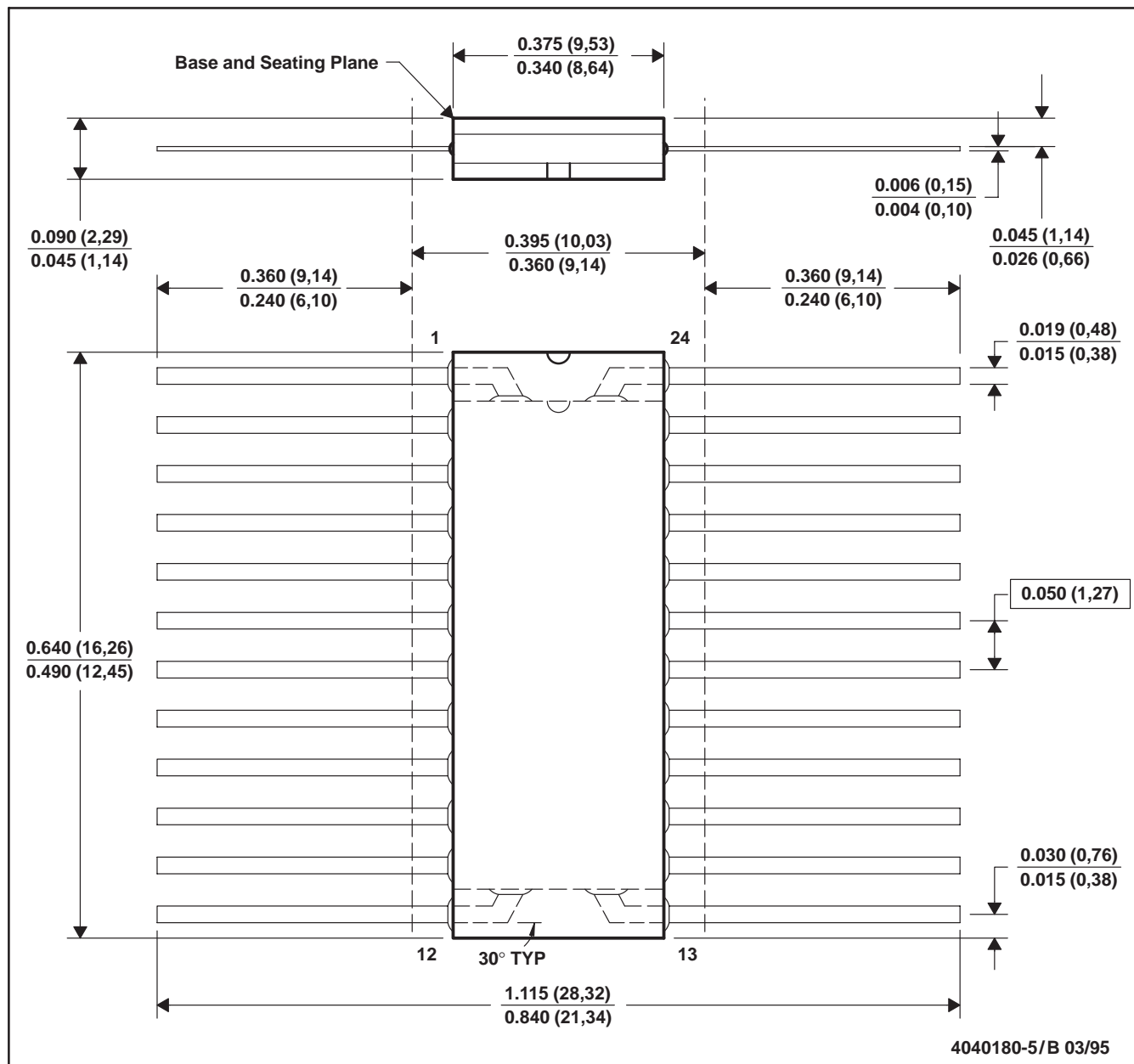


- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification.  
 E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB



## W (R-GDFP-F24)

## CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
  - E. Index point is provided on cap for terminal identification only.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

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DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
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OMAP Mobile Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
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